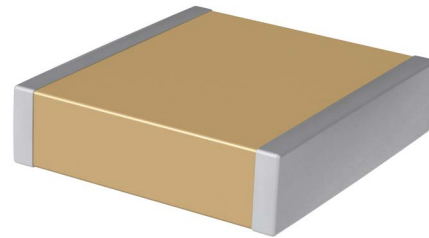


## High Voltage, U2J Dielectric, 2,000 VDC (Commercial & Automotive Grade)

### Overview

KEMET's Class I U2J High Voltage series is designed to meet the growing demand for high AC current resonant applications such as LLC resonant converters and wireless power transfer circuits in electric vehicles. By utilizing KEMET's proprietary U2J dielectric, this series provides designers with a surface mount solution with extremely low ESR and ESL with very high AC current capability. This leads to minimal  $i^2R$  heating losses which equates to higher efficiency power conversion.

U2J is not sensitive to capacitance loss with DC Bias as compared to Class II dielectric materials and retains over 99% of nominal capacitance at full rated voltage. KEMET automotive grade capacitors meet the demanding Automotive Electronics Council's AEC-Q200 qualification requirements. Capacitance change is limited to  $-750 \pm 120$  ppm/ $^{\circ}\text{C}$  from  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . These devices are lead (Pb)-free, RoHS and REACH compliant without exception and are capable of withstanding multiple passes through a lead (Pb)-free solder reflow profile.



### Benefits

- AEC-Q200 automotive qualified
- Very High ripple current capability
- Extremely low effective series resistance (ESR)
- Extremely low effective series inductance (ESL)
- Retains over 99% of nominal capacitance at full rated voltage
- Small predictable and linear capacitance change with respect to temperature  $< -750 \pm 120$  ppm/ $^{\circ}\text{C}$
- Operating temperature range of  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- Lead (Pb)-free, RoHS, and REACH Compliant

### Applications

- Wide bandgap (WBG), silicon carbide (SiC) and gallium nitride (GaN) systems
- EV/HEV (drive systems, charging)
- Wireless charging
- Power converters
- Inverters
- LLC resonant converters

## Ordering Information

| C       | 3640                | C                     | 153   | J   | G                   | J          | A                    | C                  | TU  |
|---------|---------------------|-----------------------|---|---|---------------------|------------|----------------------|--------------------|---|
| Ceramic | Case Size (L" x W") | Specification/ Series | Capacitance Code (pF)                       | Capacitance Tolerance <sup>1</sup>                    | Rated Voltage (VDC) | Dielectric | Failure Rate/ Design | Termination Finish | Packaging/ Grade (C-Spec)                     |
| C       | 3640                | C = Standard          | Two significant digits and number of zeros. | F = ±1%<br>G = ±2%<br>J = ±5%<br>K = ±10%<br>M = ±20% | G = 2,000 V         | J = U2J    | A = N/A              | C = 100% Matte Sn  | See "Packaging C-Spec Ordering Options Table" |

<sup>1</sup> Additional capacitance tolerance offerings may be available. Contact KEMET for details.

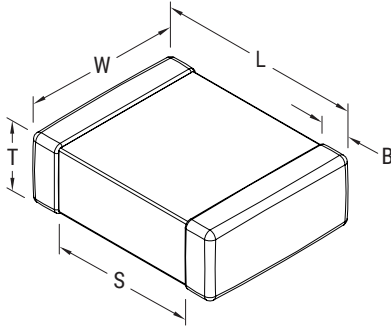
## Packaging C-Spec Ordering Options Table

| Packaging Type <sup>1</sup>   | Packaging/Grade Ordering Code (C-Spec) |
|-------------------------------|--|
| Commercial Grade              |  |
| 7" Reel/Unmarked              | TU                                     |
| 13" Reel/Unmarked             | 7210                                   |
| Automotive Grade <sup>1</sup> |  |
| 7" Reel                       | AUTO                                   |
| 13" Reel/Unmarked             | AUTO7210                               |

<sup>1</sup> For additional information regarding "AUTO" C-Spec options, see "Automotive C-Spec Information."

All Automotive packaging C-Specs listed exclude the option to laser mark components. Please contact KEMET if you require a laser marked option. For more information see "Capacitor Marking".

## Dimensions – Millimeters (Inches)



| EIA Size Code | Metric Size Code | L Length                      | W Width                        | T Thickness                  | B Bandwidth                   | S Separation Minimum | Mounting Technique    |
|---------------|------------------|-------------------------------|--------------------------------|------------------------------|-------------------------------|----------------------|-----------------------|
| 3640          | 9210             | 9.10 (0.358)<br>±0.40 (0.016) | 10.20 (0.402)<br>±0.40 (0.016) | See Table 2<br>for thickness | 1.27 (0.050)<br>±0.40 (0.016) | N/A                  | Solder<br>Reflow Only |

## Qualification/Certification

Commercial grade products are subject to internal qualification. Details regarding test methods and conditions are referenced in Table 4, Performance and Reliability.

Automotive grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. For additional information regarding the Automotive Electronics Council and AEC-Q200, please visit their website at [www.aecouncil.com](http://www.aecouncil.com).

## Environmental Compliance

Lead (Pb)-free, RoHS, and REACH compliant without exemptions.



## Automotive C-Spec Information

KEMET automotive grade products meet or exceed the requirements outlined by the Automotive Electronics Council. Details regarding test methods and conditions are referenced in document AEC-Q200, Stress Test Qualification for Passive Components. These products are supported by a Product Change Notification (PCN) and Production Part Approval Process warrant (PPAP).

Automotive products offered through our distribution channel have been assigned an inclusive ordering code C-Spec, "AUTO." This C-Spec was developed in order to better serve small and medium-sized companies that prefer an automotive grade component without the requirement to submit a customer Source Controlled Drawing (SCD) or specification for review by a KEMET engineering specialist. This C-Spec is therefore not intended for use by KEMET OEM automotive customers and are not granted the same "privileges" as other automotive C-Specs. Customer PCN approval and PPAP request levels are limited (see details below.)

### Product Change Notification (PCN)

The KEMET product change notification system is used to communicate primarily the following types of changes:

- Product/process changes that affect product form, fit, function, and/or reliability
- Changes in manufacturing site
- Product obsolescence

| KEMET Automotive C-Spec     | Customer Notification Due To:    |               | Days Prior To Implementation |
|-----------------------------|----------------------------------|---------------|------------------------------|
|                             | Process/Product change           | Obsolescence* |                              |
| KEMET assigned <sup>1</sup> | Yes (with approval and sign off) | Yes           | 180 days minimum             |
| AUTO                        | Yes (without approval)           | Yes           | 90 days minimum              |

<sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

### Production Part Approval Process (PPAP)

The purpose of the Production Part Approval Process is:

- To ensure that supplier can meet the manufacturability and quality requirements for the purchased parts.
- To provide the evidence that all customer engineering design records and specification requirements are properly understood and fulfilled by the manufacturing organization.
- To demonstrate that the established manufacturing process has the potential to produce the part.

| KEMET Automotive C-Spec     | PPAP (Product Part Approval Process) Level |   |   |   |   |
|-----------------------------|--|---|---|---|---|
|                             | 1  | 2 | 3 | 4 | 5 |
| KEMET assigned <sup>1</sup> | ●  | ● | ● | ● | ● |
| AUTO                        |  |   | ○ |   |   |

<sup>1</sup> KEMET assigned C-Specs require the submittal of a customer SCD or customer specification for review. For additional information contact KEMET.

- Part number specific PPAP available
- Product family PPAP only

**Table 1 – Capacitance Range/Selection Waterfall**

| Capacitance | Cap Code | Case Size/<br>Series  | C3640  |
|-------------|----------|-----------------------|--|
|             |          | Voltage Code          | G  |
|             |          | Rated Voltage (VDC)   | 2,000  |
|             |          | Capacitance Tolerance | Product Availability and Chip Thickness Codes<br>See Table 2 for Chip Thickness Dimensions |
| 15,000 pF   | 153      | F   G   J   K   M     | MC   |
| Capacitance | Cap Code | Rated Voltage (VDC)   | 2,000  |
|             |          | Voltage Code          | G  |
|             |          | Case Size/<br>Series  | C3640  |

These products are protected under US Patent 7,172,985 & 7,670,981, other patents pending, and any foreign counterparts.

**Table 2 – Chip Thickness/Tape & Reel Packaging Quantities**

| Thickness Code | Case Size <sup>1</sup> | Thickness ± Range (mm) | Paper Quantity |          | Plastic Quantity |          |
|----------------|------------------------|------------------------|----------------|----------|------------------|----------|
|                |                        |                        | 7" Reel        | 13" Reel | 7" Reel          | 13" Reel |
| MC             | 3640                   | 2.50 ± 0.20            | 0              | 0        | 250              | 1,000    |
| Thickness Code | Case Size <sup>1</sup> | Thickness ± Range (mm) | 7" Reel        | 13" Reel | 7" Reel          | 13" Reel |
|                |                        |                        | Paper Quantity |          | Plastic Quantity |          |

**Table 3 – Chip Capacitor Land Pattern Design Recommendations per IPC-7351**

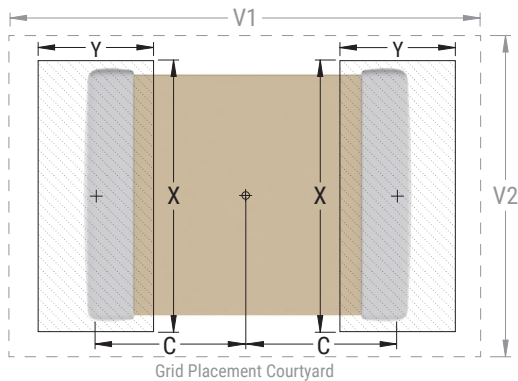
| EIA Size Code | Metric Size Code | Density Level A:<br>Maximum (Most)<br>Land Protrusion (mm) |      |       |       |       | Density Level B:<br>Median (Nominal)<br>Land Protrusion (mm) |      |       |       |       | Density Level C:<br>Minimum (Least)<br>Land Protrusion (mm) |      |       |       |       |
|---------------|------------------|--|------|-------|-------|-------|--|------|-------|-------|-------|---|------|-------|-------|-------|
|               |                  | C  | Y    | X     | V1    | V2    | C  | Y    | X     | V1    | V2    | C   | Y    | X     | V1    | V2    |
| 3640          | 9210             | 4.45   | 1.70 | 10.70 | 11.60 | 11.70 | 4.35   | 1.50 | 10.60 | 10.70 | 11.10 | 4.25  | 1.30 | 10.50 | 10.00 | 10.80 |

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes. KEMET only recommends wave soldering of EIA 0603, 0805, and 1206 case sizes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

**Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations, the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).

Image below based on Density Level B for an EIA 1210 case size.



## Soldering Process

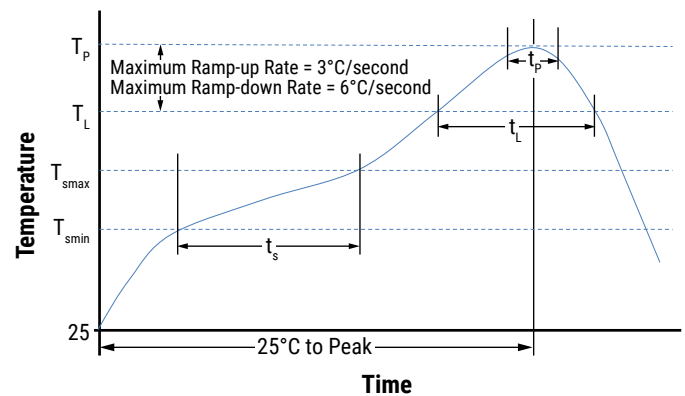
### Recommended Soldering Technique:

- Solder reflow only

### Recommended Reflow Soldering Profile:

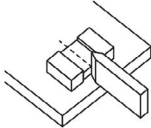
The KEMET families of surface mount multilayer ceramic capacitors (SMD MLCCs) are compatible with wave (single or dual), convection, IR or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020 standard for moisture sensitivity testing. These devices can safely withstand a maximum of three reflow passes at these conditions.

| Profile Feature                                       | Termination Finish |                    |
|---|--------------------|--------------------|
|   | SnPb               | 100% Matte Sn      |
| <b>Preheat/Soak</b>                                   |                    |                    |
| Temperature Minimum ( $T_{Smin}$ )                    | 100°C              | 150°C              |
| Temperature Maximum ( $T_{Smax}$ )                    | 150°C              | 200°C              |
| Time ( $t_s$ ) from $T_{Smin}$ to $T_{Smax}$          | 60 – 120 seconds   | 60 – 120 seconds   |
| Ramp-Up Rate ( $T_L$ to $T_P$ )                       | 3°C/second maximum | 3°C/second maximum |
| Liquidous Temperature ( $T_L$ )                       | 183°C              | 217°C              |
| Time Above Liquidous ( $t_L$ )                        | 60 – 150 seconds   | 60 – 150 seconds   |
| Peak Temperature ( $T_P$ )                            | 235°C              | 260°C              |
| Time Within 5°C of Maximum Peak Temperature ( $t_p$ ) | 20 seconds maximum | 30 seconds maximum |
| Ramp-Down Rate ( $T_P$ to $T_L$ )                     | 6°C/second maximum | 6°C/second maximum |
| Time 25°C to Peak Temperature                         | 6 minutes maximum  | 8 minutes maximum  |



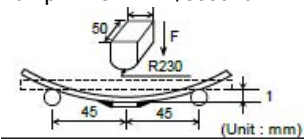
Note: All temperatures refer to the center of the package, measured on the capacitor body surface that is facing up during assembly reflow.

**Table 4 – Performance & Reliability: Test Methods and Conditions**

| Stress  | Reference         | Test Condition   | Limits  |                  |      |       |                                  |       |   |                   |   |        |   |
|---|-------------------|--|---|------------------|------|-------|----------------------------------|-------|---|-------------------|---|--------|---|
| Visual & Mechanical                                 | KEMET Internal    | No defects that may affect performance (10X)   | Dimensions according KEMET Spec Sheet   |                  |      |       |                                  |       |   |                   |   |        |   |
| Capacitance (Cap)                                   | KEMET Internal    | $C \leq 1,000 \text{ pF}$<br>Frequency: 1 MHz $\pm 100 \text{ kHz}$<br>Voltage*: 1.0 V <sub>rms</sub> $\pm 0.2 \text{ V}$<br>$C > 1,000 \text{ pF}$<br>Frequency: 1 kHz $\pm 50 \text{ Hz}$<br>Voltage: 1.0 V <sub>rms</sub> $\pm 0.2 \text{ V}$<br>* See part number specification sheet for voltage  | Within Tolerance  |                  |      |       |                                  |       |   |                   |   |        |   |
| Dissipation Factor (DF)                             | KEMET Internal    | $C \leq 1,000 \text{ pF}$<br>Frequency: 1 MHz $\pm 100 \text{ kHz}$<br>Voltage*: 1.0 V <sub>rms</sub> $\pm 0.2 \text{ V}$<br>$C > 1,000 \text{ pF}$<br>Frequency: 1 kHz $\pm 50 \text{ Hz}$<br>Voltage: 1.0 V <sub>rms</sub> $\pm 0.2 \text{ V}$<br>* See part number specification sheet for voltage  | Within Specification<br>Dissipation factor (DF) maximum limit at 25°C = 0.1%  |                  |      |       |                                  |       |   |                   |   |        |   |
| Insulation Resistance (IR)                          | KEMET Internal    | Rated voltage applied for 120 $\pm 5$ seconds at 25°C  | Within Specification<br>To obtain IR limit, divide M $\Omega$ - $\mu\text{F}$ value by the capacitance and compare to G $\Omega$ limit. Select the lower of the two limits:<br>1,000 megohm microfarads or 100 G $\Omega$ . |                  |      |       |                                  |       |   |                   |   |        |   |
| Temperature Coefficient of Capacitance (TCC)        | KEMET Internal    | Capacitance change with reference to +25°C and 0 VDC applied.<br>* See part number specification sheet for voltage<br><table border="1" style="margin: 10px auto;"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>+25°C</td> </tr> <tr> <td>2</td> <td>-55°C</td> </tr> <tr> <td>3</td> <td>+25°C (Reference)</td> </tr> <tr> <td>4</td> <td>+125°C</td> </tr> </tbody> </table> | Step  | Temperature (°C) | 1    | +25°C | 2                                | -55°C | 3 | +25°C (Reference) | 4 | +125°C | Within Specification: -750 $\pm 120$ ppm/°C |
| Step  | Temperature (°C)  |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| 1   | +25°C             |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| 2   | -55°C             |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| 3   | +25°C (Reference) |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| 4   | +125°C            |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| Dielectric Withstanding Voltage (DWV)               | KEMET Internal    | 120% of rated voltage (5 $\pm 1$ seconds and charge/discharge not exceeding 50 mA)   | Cap: Initial Limit<br>DF: Initial Limit<br>IR: Initial Limit<br><br>Withstand test voltage without insulation breakdown or damage.  |                  |      |       |                                  |       |   |                   |   |        |   |
| Aging Rate (Maximum % Capacitance Loss/Decade Hour) | KEMET Internal    | Maximum % capacitance loss/decade hour   | 0.1% Loss/Decade Hour   |                  |      |       |                                  |       |   |                   |   |        |   |
| Terminal Strength                                   | KEMET Internal    | Shear stress test per specific case size, Time: 60 $\pm 1$ seconds<br><table border="1" style="margin: 10px auto;"> <thead> <tr> <th>Case Size</th> <th>Force</th> </tr> </thead> <tbody> <tr> <td>3640</td> <td>18N</td> </tr> </tbody> </table>   | Case Size   | Force            | 3640 | 18N   | No evidence of mechanical damage |       |   |                   |   |        |   |
| Case Size   | Force             |  |   |                  |      |       |                                  |       |   |                   |   |        |   |
| 3640  | 18N               |  |   |                  |      |       |                                  |       |   |                   |   |        |   |



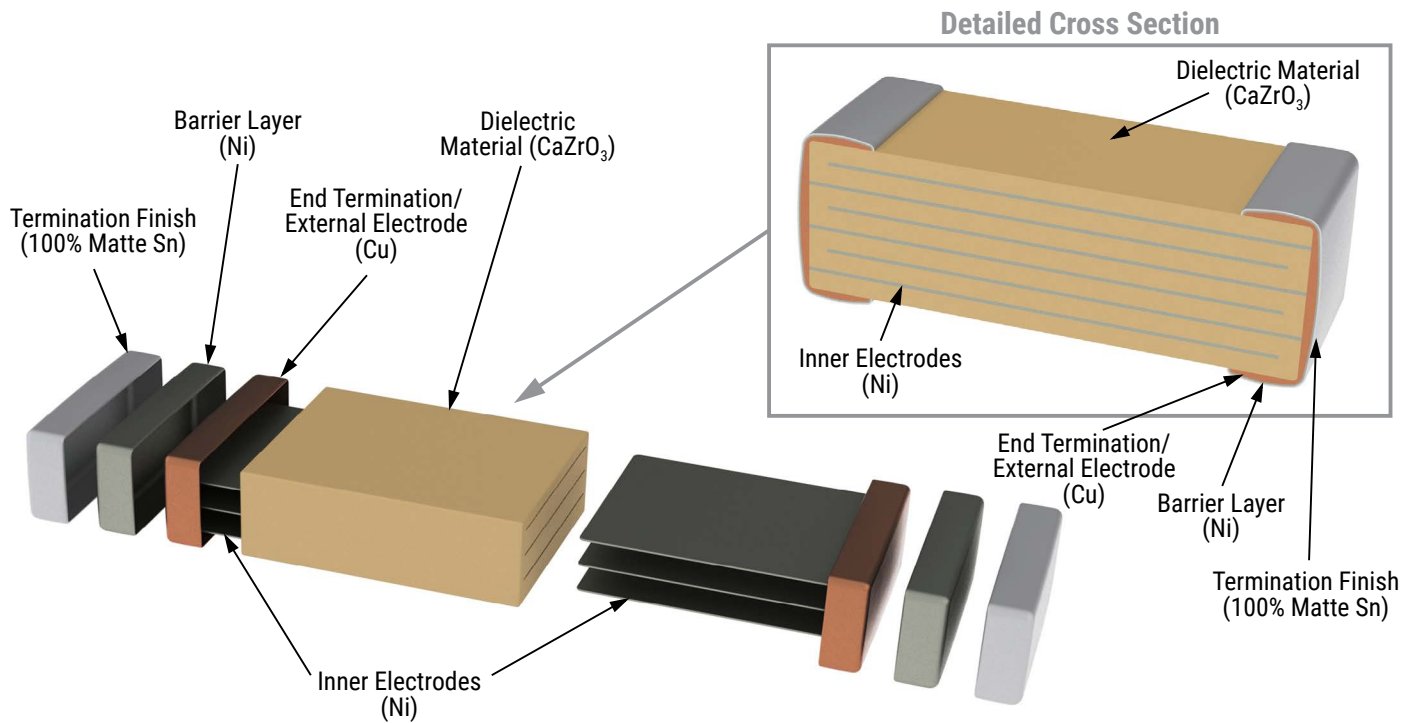
**Table 4 – Performance & Reliability: Test Methods and Conditions cont.**

| Stress                 | Reference                 | Test Condition  | Limits   |
|------------------------|---------------------------|---|--|
| Board Flex             | AEC-Q200-005              | 3.0 mm minimum<br>Test Time: 60 ±5 seconds<br>Ramp Time: 1 mm/second<br> | No evidence of mechanical damage   |
| Solderability          | J-STD-002                 | Condition: 4 hours ±15 minutes at 155°C dry bake apply all methods<br>Test 245 ±5°C (SnPb & Pb-Free)  | Visual Inspection.<br>95% coverage on termination.<br>No leaching  |
| Temperature Cycling    | JESD22<br>Method JA-104   | 1,000 cycles (-55°C to +125°C)<br>2 - 3 cycles per hour<br>Soak Time: 1 or 5 minutes  | Measurement at 24 hours ±4 hours after test conclusion.<br>Cap: Initial Limit<br>DF: Initial Limit<br>IR: Initial Limit  |
| Biased Humidity        | MIL-STD-202<br>Method 103 | Load Humidity: 1,000 hours<br>85°C/85% RH and rated voltage.<br>Low Volt Humidity: 1,000 hours<br>85°C/85% RH and 1.5 V.                                  | Measurement at 24 hours ±4 hours after test conclusion.<br>Within Post Environmental Limits<br>Cap: ±0.3% or ±0.25 pF shift<br>IR: 10% of Initial Limit<br>DF Limits Maximum: 0.5% |
| High Temperature Life  | MIL-STD-202<br>Method 108 | 1,000 hours at 125°C with 2 X rated voltage applied   | Within Post Environmental Limits<br>Cap: ±0.3% or ±0.25 pF shift<br>IR: 10% of Initial Limit<br>DF: 0.5%   |
| Storage Life           |                           | 1,000 hours at 125°C, Unpowered   |  |
| Vibration              | MIL-STD-202<br>Method 204 | 5 g's for 20 minutes, 12 cycles each of 3 orientations.<br>Test from 10 – 2,000 Hz  | Cap: Initial Limit<br>DF: Initial Limit<br>IR: Initial Limit   |
| Mechanical Shock       | MIL-STD-202<br>Method 213 | 1,500 g's 0.5 ms Half-sine, Velocity Change 15.4 ft/second (Condition F)  | Cap: Initial Limit<br>DF: Initial Limit<br>IR: Initial Limit   |
| Resistance to Solvents | MIL-STD-202<br>Method 215 | Add Aqueous wash chemical OKEMCLEAN (A 6% concentrated Oakite cleaner) or equivalent.<br>Do not use banned solvents                                       | Readable marking, no discoloration or stains.<br>No physical damage.   |

## Storage and Handling

Ceramic chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 70% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulfur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within 1.5 years of receipt.

## Construction



## Capacitor Marking (Optional)

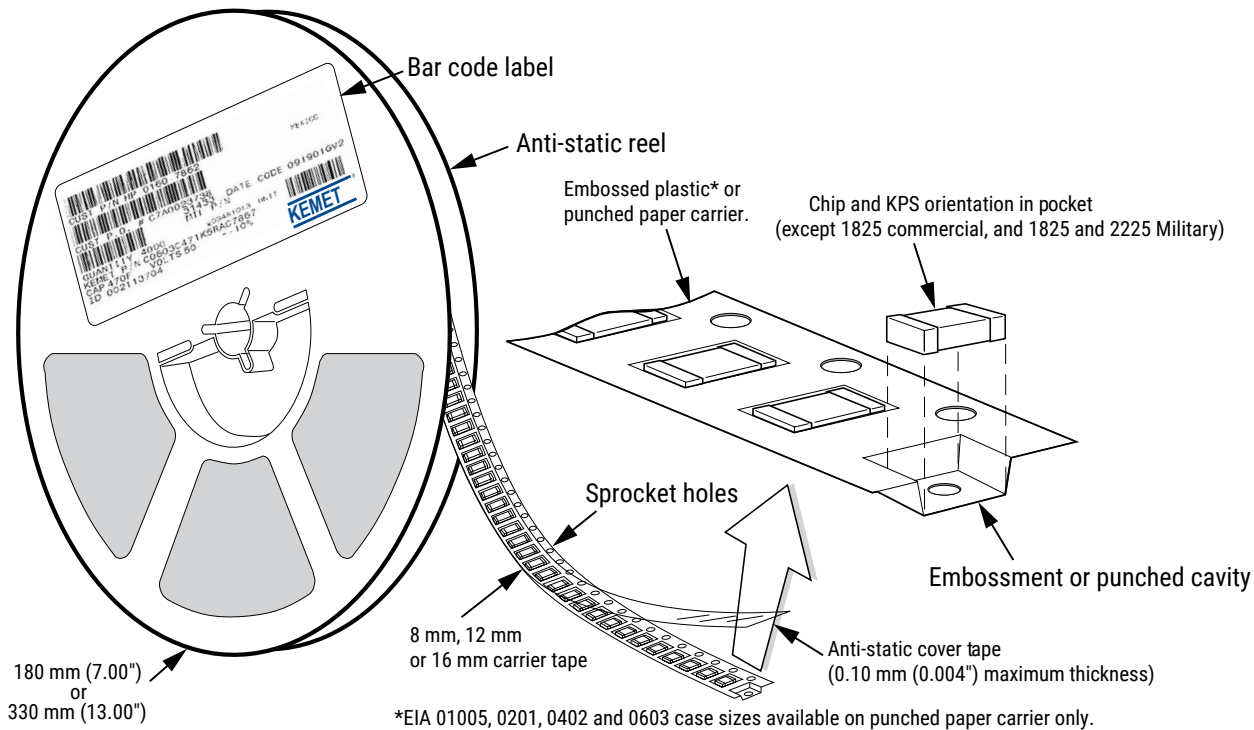
Laser marking option is not available on:

- C0G, U2J, Ultra Stable X8R, and Y5V dielectric devices
- EIA 0402 case size devices
- EIA 0603 case size devices with flexible termination option
- KPS commercial and automotive grade stacked devices

These capacitors are supplied unmarked only.

## Tape & Reel Packaging Information

KEMET offers multilayer ceramic chip capacitors packaged in 8, 12 and 16 mm tape on 7" and 13" reels in accordance with EIA Standard 481. This packaging system is compatible with all tape-fed automatic pick and place systems. See Table 2 for details on reeling quantities for commercial chips.



**Table 5 – Carrier Tape Configuration, Embossed Plastic & Punched Paper (mm)**

| EIA Case Size     | Tape Size (W)* | Embossed Plastic         |          | Punched Paper            |          |
|-------------------|----------------|--------------------------|----------|--------------------------|----------|
|                   |                | 7" Reel                  | 13" Reel | 7" Reel                  | 13" Reel |
|                   |                | Pitch (P <sub>1</sub> )* |          | Pitch (P <sub>1</sub> )* |          |
| 01005 – 0402      | 8              |                          |          | 2                        | 2        |
| 0603              | 8              |                          |          | 2/4                      | 2/4      |
| 0805              | 8              | 4                        | 4        | 4                        | 4        |
| 1206 – 1210       | 8              | 4                        | 4        | 4                        | 4        |
| 1805 – 1808       | 12             | 4                        | 4        |                          |          |
| ≥ 1812            | 12             | 8                        | 8        |                          |          |
| KPS 1210          | 12             | 8                        | 8        |                          |          |
| KPS 1812 and 2220 | 16             | 12                       | 12       |                          |          |
| Array 0612        | 8              | 4                        | 4        |                          |          |

### New 2 mm Pitch Reel Options\*

| Packaging Ordering Code (C-Spec) | Packaging Type/Options             |
|----------------------------------|------------------------------------|
| C-3190                           | Automotive grade 7" reel unmarked  |
| C-3191                           | Automotive grade 13" reel unmarked |
| C-7081                           | Commercial grade 7" reel unmarked  |
| C-7082                           | Commercial grade 13" reel unmarked |

\* 2 mm pitch reel only available for 0603 EIA case size.  
 2 mm pitch reel for 0805 EIA case size under development.

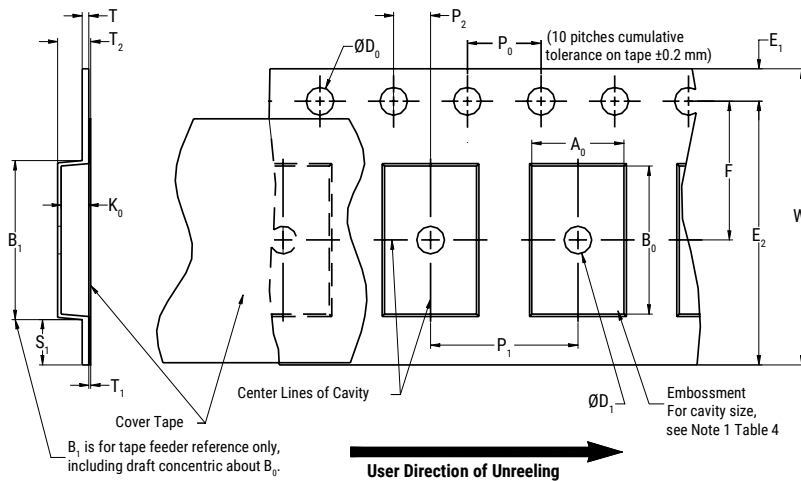
### Benefits of Changing from 4 mm to 2 mm Pitching Spacing

- Lower placement costs.
- Double the parts on each reel results in fewer reel changes and increased efficiency.
- Fewer reels result in lower packaging, shipping and storage costs, reducing waste.

\*Refer to Figures 1 and 2 for W and P<sub>1</sub> carrier tape reference locations.

\*Refer to Tables 6 and 7 for tolerance specifications.

**Figure 1 – Embossed (Plastic) Carrier Tape Dimensions**

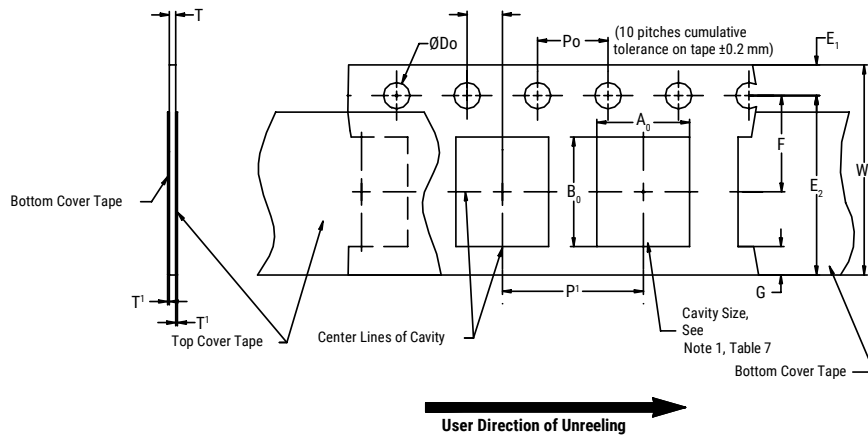


**Table 6 – Embossed (Plastic) Carrier Tape Dimensions**  
 Metric will govern

| Constant Dimensions – Millimeters (Inches) |                                       |                         |                              |                             |                              |                       |                         |                    |                  |
|--|---------------------------------------|-------------------------|------------------------------|-----------------------------|------------------------------|-----------------------|-------------------------|--------------------|------------------|
| Tape Size                                  | $D_0$                                 | $D_1$ Minimum<br>Note 1 | $E_1$                        | $P_0$                       | $P_2$                        | R Reference<br>Note 2 | $S_1$ Minimum<br>Note 3 | T<br>Maximum       | $T_1$<br>Maximum |
| 8 mm                                       | 1.5 +0.10/-0.0<br>(0.059 +0.004/-0.0) | 1.0<br>(0.039)          | 1.75 ±0.10<br>(0.069 ±0.004) | 4.0 ±0.10<br>(0.157 ±0.004) | 2.0 ±0.05<br>(0.079 ±0.002)  | 25.0<br>(0.984)       | 0.600<br>(0.024)        | 0.600<br>(0.024)   | 0.100<br>(0.004) |
| 12 mm                                      |                                       | 1.5<br>(0.059)          |                              |                             |                              | 30<br>(1.181)         |                         |                    |                  |
| 16 mm                                      |                                       |                         |                              |                             |                              |                       |                         |                    |                  |
| Variable Dimensions – Millimeters (Inches) |                                       |                         |                              |                             |                              |                       |                         |                    |                  |
| Tape Size                                  | Pitch                                 | $B_1$ Maximum<br>Note 4 | $E_2$<br>Minimum             | F                           | $P_1$                        | $T_2$<br>Maximum      | W<br>Maximum            | $A_0, B_0$ & $K_0$ |                  |
| 8 mm                                       | Single (4 mm)                         | 4.35<br>(0.171)         | 6.25<br>(0.246)              | 3.5 ±0.05<br>(0.138 ±0.002) | 4.0 ±0.10<br>(0.157 ±0.004)  | 2.5<br>(0.098)        | 8.3<br>(0.327)          | Note 5             |                  |
| 12 mm                                      | Single (4 mm)<br>and double (8 mm)    | 8.2<br>(0.323)          | 10.25<br>(0.404)             | 5.5 ±0.05<br>(0.217 ±0.002) | 8.0 ±0.10<br>(0.315 ±0.004)  | 4.6<br>(0.181)        | 12.3<br>(0.484)         |                    |                  |
| 16 mm                                      | Triple (12 mm)                        | 12.1<br>(0.476)         | 14.25<br>(0.561)             | 7.5 ±0.05<br>(0.138 ±0.002) | 12.0 ±0.10<br>(0.157 ±0.004) | 4.6<br>(0.181)        | 16.3<br>(0.642)         |                    |                  |

- The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of the embossment location and the hole location shall be applied independently of each other.
- The tape with or without components shall pass around R without damage (see Figure 6.)
- If  $S_1 < 1.0$  mm, there may not be enough area for a cover tape to be properly applied (see EIA Standard 481, paragraph 4.3, section b.)
- $B_1$  dimension is a reference dimension for tape feeder clearance only.
- The cavity defined by  $A_0, B_0$  and  $K_0$  shall surround the component with sufficient clearance that:
  - the component does not protrude above the top surface of the carrier tape.
  - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 3.)
  - lateral movement of the component is restricted to 0.5 mm maximum for 8 and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 4.)
  - for KPS product,  $A_0$  and  $B_0$  are measured on a plane 0.3 mm above the bottom of the pocket.
  - see addendum in EIA Standard 481 for standards relating to more precise taping requirements.

**Figure 2 – Punched (Paper) Carrier Tape Dimensions**



**Table 7 – Punched (Paper) Carrier Tape Dimensions**

Metric will govern

| Constant Dimensions – Millimeters (Inches) |                                       |                              |                             |                             |                            |                 |                    |
|--|---------------------------------------|------------------------------|-----------------------------|-----------------------------|----------------------------|-----------------|--------------------|
| Tape Size                                  | $D_0$                                 | $E_1$                        | $P_0$                       | $P_2$                       | $T_1$ Maximum              | G Minimum       | R Reference Note 2 |
| 8 mm                                       | 1.5 +0.10 -0.0<br>(0.059 +0.004 -0.0) | 1.75 ±0.10<br>(0.069 ±0.004) | 4.0 ±0.10<br>(0.157 ±0.004) | 2.0 ±0.05<br>(0.079 ±0.002) | 0.10<br>(0.004)<br>maximum | 0.75<br>(0.030) | 25<br>(0.984)      |
| Variable Dimensions – Millimeters (Inches) |                                       |                              |                             |                             |                            |                 |                    |
| Tape Size                                  | Pitch                                 | E2 Minimum                   | F                           | $P_1$                       | T Maximum                  | W Maximum       | $A_0 B_0$          |
| 8 mm                                       | Half (2 mm)                           | 6.25<br>(0.246)              | 3.5 ±0.05<br>(0.138 ±0.002) | 2.0 ±0.05<br>(0.079 ±0.002) | 1.1<br>(0.098)             | 8.3<br>(0.327)  | Note 1             |
| 8 mm                                       | Single (4 mm)                         |                              |                             | 4.0 ±0.10<br>(0.157 ±0.004) |                            |                 |                    |

- The cavity defined by  $A_0$ ,  $B_0$  and  $T$  shall surround the component with sufficient clearance that:
  - the component does not protrude beyond either surface of the carrier tape.
  - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - rotation of the component is limited to 20° maximum (see Figure 3.)
  - lateral movement of the component is restricted to 0.5 mm maximum (see Figure 4.)
  - see addendum in EIA Standard 481 for standards relating to more precise taping requirements.
- The tape with or without components shall pass around R without damage (see Figure 6.)

## Packaging Information Performance Notes

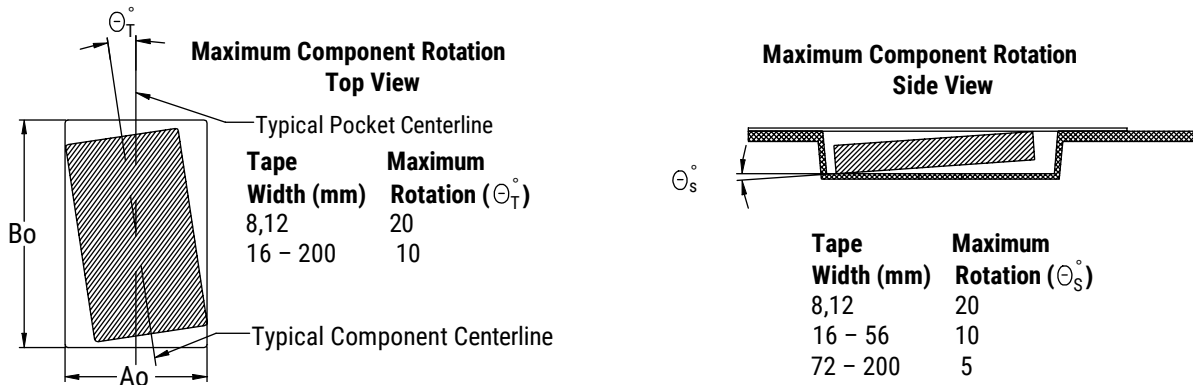
- Cover Tape Break Force:** 1.0 kg minimum.
- Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

| Tape Width   | Peel Strength                    |
|--------------|----------------------------------|
| 8 mm         | 0.1 to 1.0 Newton (10 to 100 gf) |
| 12 and 16 mm | 0.1 to 1.3 Newton (10 to 130 gf) |
| 24 mm        | 0.1 to 1.6 Newton (10 to 160 gf) |

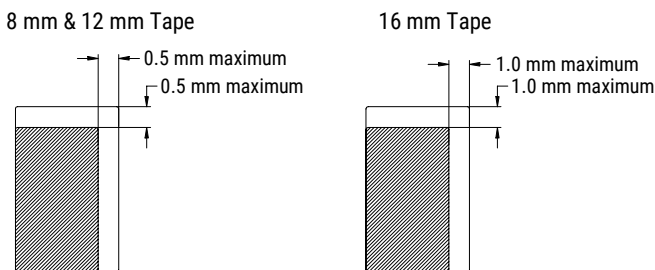
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

- Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

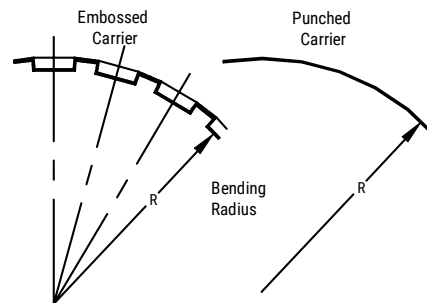
### Figure 3 – Maximum Component Rotation



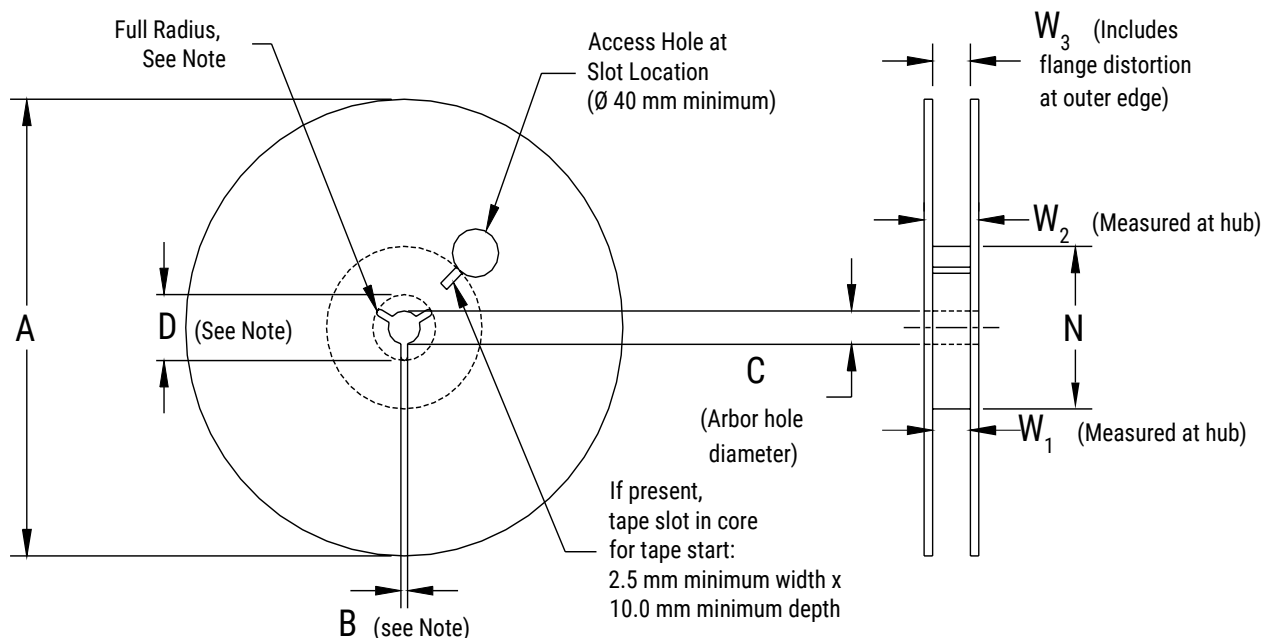
### Figure 4 – Maximum Lateral Movement



### Figure 5 – Bending Radius



**Figure 6 – Reel Dimensions**



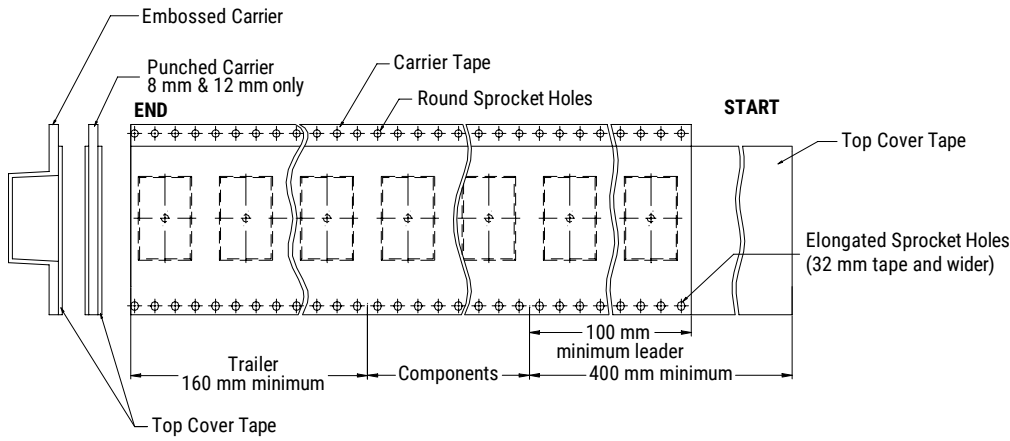
Note: Drive spokes optional; if used, dimensions B and D shall apply.

**Table 8 – Reel Dimensions**

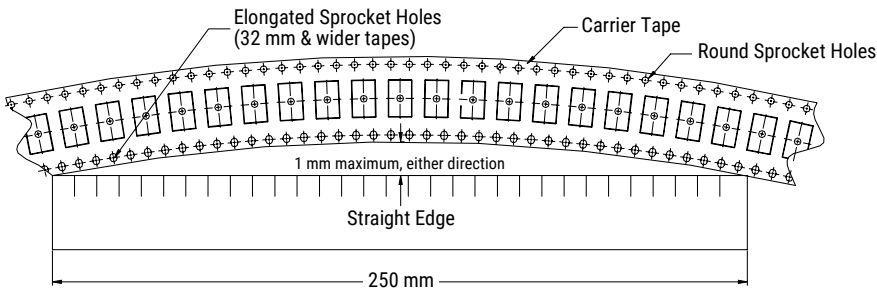
Metric will govern

| Constant Dimensions – Millimeters (Inches) |   |                                       |  |   |
|--|---|---------------------------------------|--|---|
| Tape Size                                  | A   | B Minimum                             | C                                      | D Minimum   |
| 8 mm                                       | 178 ±0.20<br>(7.008 ±0.008)<br>or<br>330 ±0.20<br>(13.000 ±0.008) | 1.5<br>(0.059)                        | 13.0 +0.5/-0.2<br>(0.521 +0.02/-0.008) | 20.2<br>(0.795)                                   |
| 12 mm                                      |   |                                       |  |   |
| 16 mm                                      |   |                                       |  |   |
| Variable Dimensions – Millimeters (Inches) |   |                                       |  |   |
| Tape Size                                  | N Minimum   | W <sub>1</sub>                        | W <sub>2</sub> Maximum                 | W <sub>3</sub>                                    |
| 8 mm                                       | 50<br>(1.969)   | 8.4 +1.5/-0.0<br>(0.331 +0.059/-0.0)  | 14.4<br>(0.567)                        | Shall accommodate tape width without interference |
| 12 mm                                      |   | 12.4 +2.0/-0.0<br>(0.488 +0.078/-0.0) | 18.4<br>(0.724)                        |   |
| 16 mm                                      |   | 16.4 +2.0/-0.0<br>(0.646 +0.078/-0.0) | 22.4<br>(0.882)                        |   |

**Figure 7 – Tape Leader & Trailer Dimensions**



**Figure 8 – Maximum Camber**





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